PG PUB text search

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L20	26	((heating cooling) with wafer same (thermion electron)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:46
L21	153	((heating cooling) with wafer with chuck).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:46
L22	5	((heating cooling) with wafer with chuck).clm. and (electron thermion$4).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:46

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3	"20050083634"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 10:07
L2	67384	"118"/$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 10:57
L3	591	2 and (heat$3 with (plasma electron thermion$2)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 10:59
L4	151	2 and (heat$3 with (electron thermion$2)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:00
L5	98	4 and (apparatus device).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 10:59
L6	85	4 and (apparatus).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 10:59
L7	783	"313"/$.ccls. and (heat$3 with (electron thermion$2)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:01
L8	117	"313"/$.ccls. and (heat$3 with (thermion$2)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:01
L9	1	"313"/$.ccls. and (heat$3 with (thermion$2) with wafer).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:01

L10	2	"313"/$.ccls. and (heat$3 with (electron thermion$2) with wafer).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:03
L11	2	"313"/$.ccls. and (heat$3 with (electron thermion$2)).clm. and heat$3 with (electron thermion$2) with wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:04
L12	2	"315"/$.ccls. and (heat$3 with (electron thermion$2)).clm. and heat$3 with (electron thermion$2) with wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:04
L13	0	"134"/$.ccls. and (heat$3 with (electron thermion$2)).clm. and heat$3 with (electron thermion$2) with wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:04
L14	1	"445"/$.ccls. and (heat$3 with (electron thermion$2)).clm. and heat$3 with (electron thermion$2) with wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:05
L15	12	"427"/$.ccls. and (heat$3 with (electron thermion$2)).clm. and heat$3 with (electron thermion$2) with wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:13
L16	24	"438"/$.ccls. and (heat$3 with (electron thermion$2)).clm. and heat$3 with (electron thermion$2) with wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:21
L17	118	"438"/$.ccls. and (heating with cooling).clm. and heating with cooling with wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:23
L18	0	"438"/$.ccls. and (heating with cooling).clm. and heating with cooling with wafer and thermion$2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:23
L19	36	"438"/$.ccls. and (heating with cooling).clm. and heating with cooling with wafer same (lamp light electron ion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:44

L20	26	((heating cooling) with wafer same (thermion electron)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:46
L21	153	((heating cooling) with wafer with chuck).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:46
L22	5	((heating cooling) with wafer with chuck).clm. and (electron thermion$4).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:46
S1	3691	(electron thermion$2) with (bomb$3 bombard$3 accelerat$4 imping$4 collid$4) with heat$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:04
S2	4646	(electron thermion$2) with (bomb$3 bombard$3 accelerat$4 imping$4 collid$4) with (heat$3 temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/22 10:04
S3	945	S2 and ((heat$3 temperature) near5 control$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/22 11:33
S4	22	S3 and ((semiconductor silicon wafer) near5 heating with electron)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/22 12:33
S5	27216	"432"/$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/22 11:53
S6	496	S5 and (heat$3 near5 chamber).clm. and (chamber near5 wall).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/22 12:12
S7	64	S5 and (heat$3 near5 chamber).clm. and (chamber near5 wall near5 (shape plural$4)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/22 12:10

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S8	0	S5 and (heat$3 near5 chamber). clm. and (chamber near5 wall near5 (shape plural$4)).clm. and (heat$3 with treat$4 near7 cycl$3). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/22 11:58
S9	1	S5 and (heat$3 near5 chamber). clm. and (chamber near5 wall near5 (shape plural$4)).clm. and (heat$3 with treat$4 near7 cycl$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/22 11:59
S10	24	S5 and ((chamber wall) near5 (shape$ plural$4)).clm. and ((heat$3 treat$4) near7 cycl$3). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/22 12:00
S11	20	S6 and (semiconductor silicon wafer).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/22 12:05
S12	3	S5 and (heat$3 near5 chamber). clm. and ((chamber near5 wall) and (shape near5 wall) and (wall near3 plural$4)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/22 12:10
S13	0	S5 and (heat$3 near5 chamber). clm. and ((weak$4 deform$3 stress$3) near5 (chamber wall corner section) with expan$4).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/22 12:13
S14	14	(heat$3 near5 chamber).clm. and ((weak$4 deform$3 stress$3) near5 (chamber wall corner section) with expan$4).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/22 12:13
S15	124	"36370"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/22 12:33
S16	3	"2000036370"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/22 12:35
S17	13883	h05b003$.ipc.	JPO	OR	ON	2006/03/22 12:36
S18	6834	g01k007$.ipc.	JPO	OR	ON	2006/03/22 12:36
S19	20602	S17 S18	JPO	OR	ON	2006/03/22 12:37

S20	6	S19 and (stress$4 expan$5) with chamber	JPO	OR	ON	2006/03/22 12:40
S21	1925	b23k015$.ipc.	JPO	OR	ON	2006/03/22 12:39
S22	2	S21 and (stress$4 expan$5) with chamber	JPO	OR	ON	2006/03/22 12:42
S23	2	S21 and expan$5 with wall	JPO	OR	ON	2006/03/22 12:43
S24	910626	S21 and expan$5 hear5 heat$4	JPO	OR	ON	2006/03/22 12:43
S25	5	S21 and expan$5 near5 heat$4	JPO	OR	ON	2006/03/22 12:45
S26	0	S21 and expan$5 near5 (chamber wall)	JPO	OR	ON	2006/03/22 12:46
S27	2	S21 and expan$5 near5 ring	JPO	OR	ON	2006/03/22 12:47
S28	0	S21 and expan$5 near5 bellow	JPO	OR	ON	2006/03/22 12:47
S29	0	S21 and expan$5 near5 size	JPO	OR	ON	2006/03/22 12:48
S30	4	S21 and heat$3 near5 size	JPO	OR	ON	2006/03/22 12:48
S31	172	S21 and vacuum with chamber	JPO	OR	ON	2006/03/22 12:49
S32	25	S21 and vacuum with chamber and wall	JPO	OR	ON	2006/03/22 12:49
S33	2	"20040222199"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/23 11:04
S34	1	S33 and upper with lower	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/23 11:05
S35	1	S33 and upper with lower with diameter	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/23 11:05
S36	1	S33 and (upper lower) with diameter	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/23 11:08
S37	5	furnace same ((upper with lower with diameter with chamber) same (upper near3 (larger bigger greater) near3 diameter))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/23 11:09

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S38	786	(electron thermion$2) adj (bomb$3 bombard$3 accelerat$4 imping$4 collid$4) with heat$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:46
S39	636	(electron thermion$2) adj (bomb$3 bombard$3 accelerat$4 imping$4 collid$4) with filament	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:06
S40	54	S39 same wall	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:06
S41	659	(plasma electron thermion$2) adj (bomb$3 bombard$3 accelerat$4 imping$4 collid$4) with filament	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:16
S42	0	S41 same wall with (diameter step expan$7)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:06
S43	60	S41 same wall	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:08
S44	498655	"118"/$.ccls. "427"/$.ccls. "445"/$.ccls. "313"/$.ccls. "315"/$.ccls. "134"/$.ccls. "250"/$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:15
S45	2643	(plasma electron thermion$2) with (bomb$3 bombard$3 accelerat$4 imping$4 collid$4) with filament	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:16
S46	1311	S44 and S45	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:16
S47	778	S46 and chamber	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:16

S48	282	S46 and chamber with wall	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:16
S49	37	S46 and chamber with wall with (diameter shape step expan$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:19
S50	291	S46 and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:19
S51	34	S46 and wafer with (heat$4 preheat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:42
S52	35	S46 and wafer near3 support$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:45
S53	0	S46 and wafer near3 preheat$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:45
S54	1	S45 and wafer near3 preheat$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:45
S55	229	S44 and wafer near3 preheat$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:47
S56	1	S55 and (electron thermion$2) adj (bomb$3 bombard$3 accelerat$4 imping$4 collid$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:47
S57	5542	S44 and wafer near2 heat$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 13:47

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S58	83	S57 and (electron thermion$2) adj (bomb$3 bombard$3 accelerat$4 imping$4 collid$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 14:01
S59	77	((apparatus device) with (plasma electron thermion$2) near2 heating and (vacuum evacuat$4)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 14:06
S60	5	S59 and (plasma electron thermion$2) with heat$4 with (silicon wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 14:06
S61	153	((apparatus device) with (plasma electron thermion$2) near2 heat$3 and (vacuum evacuat$4)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 10:58
S62	10	S61 and (plasma electron thermion$2) with heat$4 with (silicon wafer) not S60	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 10:57
S63	357	(plasma electron thermion$2) near2 heat$3 with (vacuum evacuat$4) and (plasma electron thermion$2) with heat$4 with (support$3 plate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 14:10
S64	34	S63 and wafer with (support$3 plate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 14:15
S65	0	("2004/0222199" | "2006/0213876").URPN.	USPAT	OR	ON	2007/08/16 14:13
S66	24	((electron thermion plasma) with heat$4 with (apparatus device) and vacuum and (support$4 hold$4) near5 wafer).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 14:21
S67	3	wafer near3 retaining adj (device apparatus fixture) with heat$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/16 14:22

S68	17	wafer near3 retaining near3 (device apparatus fixture) with heat$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 10:07